

# BEST AVAILABLE COPY

Sheet 1 of 1

Form PTO-1449 (REV. 8-83)		US Dept. of Commerce PATENT & TRADEMARK OFFICE		ATTY DOCKET NO. 105895		APPLICATION NO. 09/509,669	
INFORMATION DISCLOSURE STATEMENT  (Use several sheets if necessary)				APPLICANT(S) Akihiro MURATA et al.			
				FILING DATE April 4, 2000		GROUP 2872	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	
AV9		5,940,550	08/17/99	Plickert et al.	385	15	
AV9		5,177,753	01/05/93	Tanaka	372	36	
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	
AV9		DE 197 14 170 C1	07/30/98	GERMANY	—	—	
AV9		WO 95/25974	09/28/95	WIPO	—	—	
AV9		DE 196 16 969 A1	10/30/97	GERMANY	—	—	
AV9		GB 2 312 551 A	10/29/97	UNITED KINGDOM	—	—	
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
AV9	/	T. HAYASHI; "An Innovative Bonding Technique for Optical Chips Using Solder Bumps That Eliminate Chip Positioning Adjustments"; IEEE Transactions on Components, Hybrids, and Manufacturing Technology, April 15, 1992, No. 2, New York; pages 225-230.					
AV9	/	T. NAGATA et al.; "Single Chip Integration of LED, Waveguide and Micromirrors"; Extended Abstracts of the 1994 International Conference on Solid State Devices & Materials, Yokohama, Japan; August 23-26, 1994; pages 90-92					
EXAMINER				DATE CONSIDERED			
<i>Alexander V. Aron</i>				1/8/03			
Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							